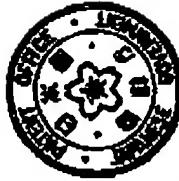


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## PATENT ABSTRACTS OF JAPAN

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(71) Applicant: MATSUSHITA ELECTRONICS

CORP

(72) Inventor: FUJI HIROYUKI

(74) Representative:

(84) Designated contracting  
states:  
  
**(54) MANUFACTURE OF  
RESIN-MOLD  
SEMICONDUCTOR DEVICE  
AND SEALING DEVICE  
USED THEREFOR**

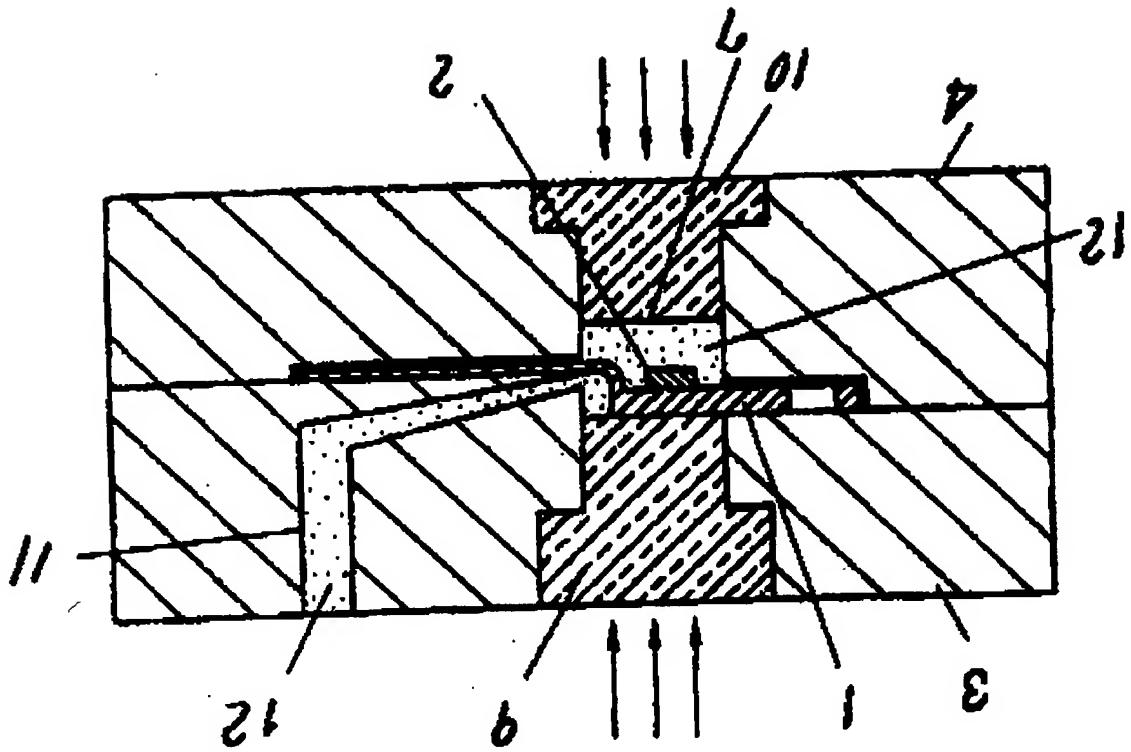
(57) Abstract:

PURPOSE: To contrive the reduction  
of the cost of resin sealing by using  
molding resin of ultraviolet-curing  
type for sealing resin so as to  
selectively cure only the molding  
resin of ultraviolet-curing type to be  
poured in the cavity.

CONSTITUTION: The built-up body of a transistor in which a transistor element 2 is bonded to a substrate supporting part 1 of the lead frame and further connection by metal thin wires has been completed is arranged between the upper and lower molding dies 3 and 4. Next, the ultraviolet-curing resin 13 is poured into the cavity 7 through a molding resin supply hole 11. After that, the sealing molds are irradiated with the ultraviolet rays as indicated by the arrows. As the resin layers 9 and 10 of the molding dies 3 and 4 consist of the resin of ultraviolet-transparent type, the ultraviolet rays penetrates through said layers 9 and 10 to reach the cavity 7. Accordingly, only the resin poured in the cavity 7 is subjected to curing reaction and is cured. In this manufacturing method, there is no waste of molding resin, and heating of the resin and of the sealing molds is unnecessary so that improvement of operation efficiency and reduction of the cost of resin sealing can be contrived.

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